Claims

1. An epoxy resin composition comprising an organopolysiloxane (A) and a polycarboxylic acid (B),

wherein

the organopolysiloxane (A) is an epoxy resin having at least a glycidyl group and/or an epoxycyclohexyl group in the molecule thereof and

the polycarboxylic acid (B) is a polycarboxylic acid having at least two or more carboxyl groups and having an aliphatic hydrocarbon group as the main skeleton.

2. The epoxy resin composition according to claim 1, which contains an acid anhydride (C).

3. The epoxy resin composition according to claim 1 or 2, wherein the polycarboxylic acid is a compound obtained by reacting a bifunctional to hexafunctional polyhydric alcohol having 5 or more carbon atoms with a saturated aliphatic cyclic acid anhydride.

4. A cured product obtained by curing the epoxy resin composition according to any one of claims 1 to 3.

5. An optical semiconductor device comprising an optical semiconductor element and the cured product according to claim 4.

Claims

1. An epoxy resin composition comprising an organopolysiloxane (A) and a polycarboxylic acid (B),

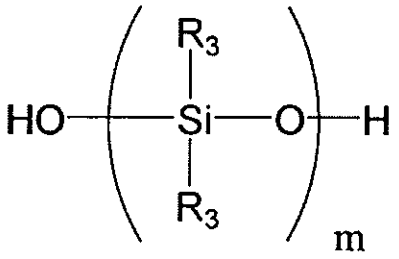
wherein

the organopolysiloxane (A) is a block-type siloxane compound that is produced by reacting an alkoxysilane compound (a) represented by the following formula (1) and a silicone oil (b) represented by the following formula (2), and performing hydrolytic condensation between alkoxy groups of the alkoxysilane compound (a), or

a block-type siloxane compound that is produced by reacting an alkoxysilane compound (a) represented by the following formula (1), a silicone oil (b) represented by the following formula (2) and an alkoxysilane compound (c) represented by the following formula (3), and performing hydrolytic condensation between alkoxy groups of the alkoxysilane compound (a) and the alkoxysilane compound (c):

$XSi(OR_2)_3$ (1)

wherein X represents an organic group having an epoxy group; and R_2 represents a linear, branched or cyclic alkyl group having 1 to 10 carbon atoms;



(2)

wherein R_3 groups which are plurally present may be the same or different from each other and represent an alkyl group having 1 to 10 carbon atoms, an aryl group having 6 to 14 carbon atoms, or an alkenyl group having 2 to 10 carbon atoms; and m represents number of repeating units; and

$R_4Si(OR_5)_3$ (3)

wherein R_4 represents a methyl group or a phenyl group; R_5 represents a linear, branched or cyclic alkyl group having 1 to 10 carbon atoms, and

the polycarboxylic acid (B) is a polycarboxylic acid having at least two or more carboxyl groups and having an aliphatic hydrocarbon group as the main skeleton.

2. The epoxy resin composition according to claim 1, which contains an acid anhydride (C).

3. The epoxy resin composition according to claim 1 or 2, wherein the polycarboxylic acid is a compound obtained by reacting a bifunctional to hexafunctional polyhydric alcohol having 5 or more carbon atoms with a saturated aliphatic cyclic acid anhydride.

4. A cured product obtained by curing the epoxy resin composition according to any one of claims 1 to 3.

5. An optical semiconductor device comprising an optical semiconductor element and the cured product according to claim 4.